LUR150G1204BO
LUR150G1204BU

SUSPM™

1200V 150A Chopper IGBT Module

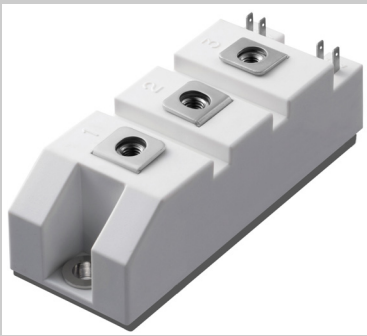
Features

- Trench IGBT technology
  - Low $V_{CE(on)}$
  - Low switching losses
  - Positive $V_{CE(on)}$ temperature coefficient
- Free wheeling diodes with fast and soft reverse recover-/y
- Industrial standard package with copper base plate

Applications

- Welder / Power Supply
- UPS / Inverter
- Industrial Motor Driver

Preliminary data



SUSPM1

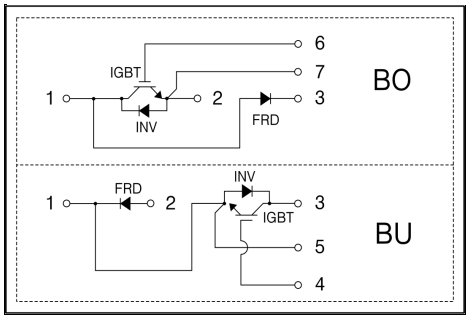
94.5 x 34.5 x 31.1 mm

Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Item	Symbol	Conditions	Value	Units
IGBT	V_{CES}		1200	V
	V_{GES}		± 20	V
	I_C	@T_j = 175 °C, T_C = 25 °C, Continuous	200	A
		@T_j = 175 °C, T_C = 80 °C, Continuous	150	A
	I_{CM}	@T_C = 80 °C, t_P = 1 ms	300	A
	T_j	Operating Junction Temperature *(1)	-40~125	°C
	P_D	@T_j = 175 °C, T_C = 25 °C	700	W
		@T_j = 175 °C, T_C = 80 °C	400	W
Diode (FRD and INV)	V_{RRM}		1200	V
	I_F		150	A
	I_{FRM}	@ t_P = 1 ms	300	A
	T_j	Operating Junction Temperature *(1)	-40~125	°C
Module	T_{stg}	Storage Temperature	-40~125	°C
	V_{iso}	@ AC 1minute	2500	V
	M_t	Main Terminal Mounting torque (M5)	2.5~5	Nm
	M_S	Heat sink Mounting torque (M6)	3.0~5	Nm
	W	Weight	180	g

Internal Circuit & Pin Description

Pin Number	Pin Name	Pin Description
1	C2E1	Out
2	E2	Negative DC Link Output
3	C1	Positive DC Link Output
4	G1	Gate Input for High-side
5	E1	Emitter Input for High-side
6	G2	Gate Input for Low-side
7	E2	Emitter Input for Low-side



(Note *1) The Maximum junction temperature of chip is 175°C

Electrical Characteristics of IGBT T_C = 25°C unless otherwise noted

Static Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
BV_{CES}	C-E Breakdown Voltage	V_{GE} = 0 V, I_C = 1mA	1200	-	-	V
I_{CES}	C-E Cut-Off Current	V_{CE} = V_{CES}, V_{GE} = 0 V	-	-	1	mA
I_{GES}	G-E Leakage Current	V_{GE} = V_{GES}, V_{CE} = 0 V	-	-	-	nA
$V_{GE(th)}$	G-E Threshold Voltage	V_{GE} = V_{CE}, I_C = 150 mA	-	7.3	-	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	I_C = 150 A, V_{GE} = 15 V, T_C= 25 °C	-	2.2	-	V
		I_C = 150 A, V_{GE} = 15 V, T_C = 125 °C	-	2.7	-	V

Dynamic Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
I_{SC}	Short Current	V_{GE} ≤15 V, V_{CC} = 800 V V_{CE} ≤ V_{CES}, T_j = 125, T_P ≤ 10us	-	1000	-	A
C_{ies}	Input Capacitance	V_{CE} = 30 V, V_{GE} = 0 V f = 1 MHz, T_C = 25 °C	-	16.3	-	nF
C_{oes}	Output Capacitance		-	0.7	-	nF
C_{res}	Reverse Transfer Capacitance		-	0.4	-	nF
t_d(on)	Turn-On Delay Time	T_C = 125 °C,R_G = 1.8 Ω L = 100 μH, V_{DC} = 600 V V_{GE} = 15 V ~ -15 V I_C = 150 A	-	237	-	ns
t_r	Rise Time		-	62	-	ns
t_d(off)	Turn-Off Delay Time		-	298	-	ns
t_f	Fall Time		-	185	-	ns
E_{on}	Turn-On Switching Loss		-	12.5	-	mJ
E_{off}	Turn-Off Switching Loss		-	9.6	-	mJ
E_{ts}	Total Switching Loss		-	22.1	-	mJ
Q_g	Total Gate Charge	V_{GE} = 0 V ~ +15 V	-	860	-	nC
Q_{ge}	Gate-Emitter Charge		-	200	-	nC
Q_{gc}	Gate-Collector Charge		-	420	-	nC

Electrical Characteristics of Diode (FRD and INV) T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions		Min	Typ	Max	Units
V_F	Diode Forward Voltage	I_F = 150 A V_{GE} = 0 V	T_C = 25 °C	-	2.3	-	V
			T_C = 125 °C	-	2.1	-	
t_{rr}	Diode Reverse Recovery Time	R_G = 1.8 Ω L = 100 μH V_{DC} = 600 V V_{GE} = 15 V ~ -15 V I_C = 150 A	T_C = 25 °C	-	153	-	ns
			T_C = 125 °C	-	422	-	
I_{RRM}	Diode Peak Reverse Recovery Current		T_C = 25 °C	-	119	-	A
			T_C = 125 °C	-	150	-	
Q_{rr}	Diode Reverse Recovery Charge		T_C = 25 °C	-	6.5	-	μC
			T_C = 125 °C	-	18.7	-	
E_{rr}	Diode Reverse Recovery Energy		T_C = 25 °C	-	1.4	-	mJ
			T_C = 125 °C	-	6.4	-	

Thermal Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
$R_{th(J-C)}$	IGBT Thermal Resistance	Junction-to-Case	-	0.21	-	°C/W
$R_{th(J-C)D}$	Diode Thermal Resistance (FRD and INV)	Junction-to-Case	-	0.39	-	°C/W

* This specifications may not be considered as an assurance of characteristics and may not have same characteristics in case of using different test systems from @LSIS. We therefore strongly recommend prior consultation of our engineers.

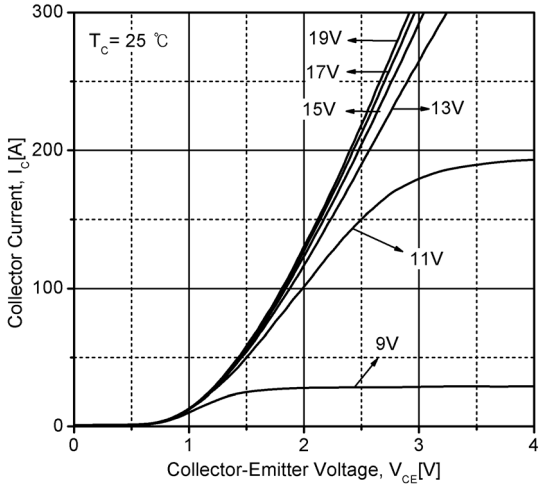


Fig 1. Typical IGBT Output Characteristics

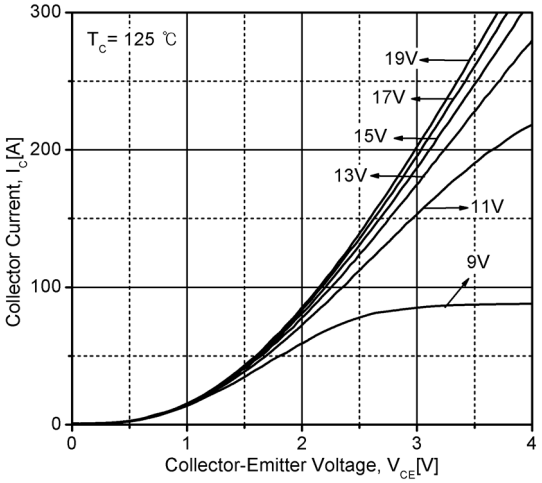


Fig 2. Typical IGBT Output Characteristics

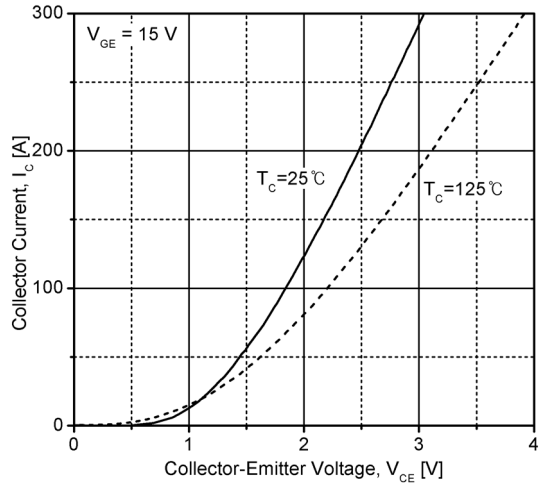


Fig 3. Typical IGBT Output Characteristics

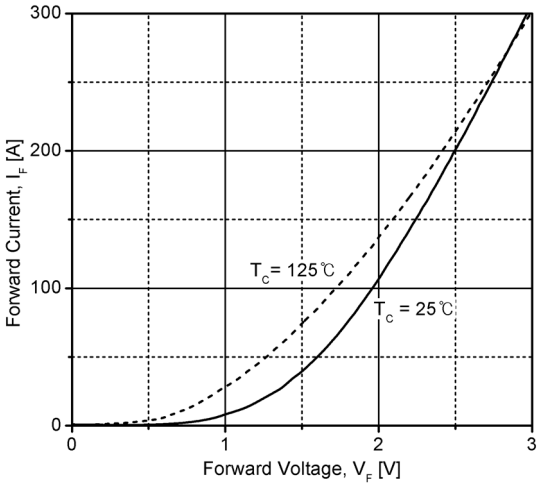


Fig 4. Typical Diode Forward Characteristics

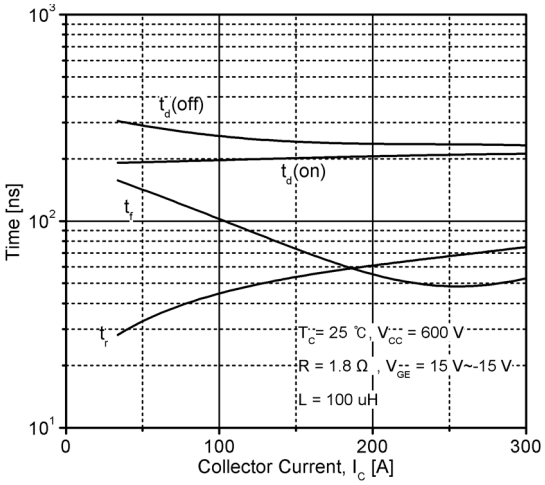


Fig 5. Typical Switching Time vs. Collector Current

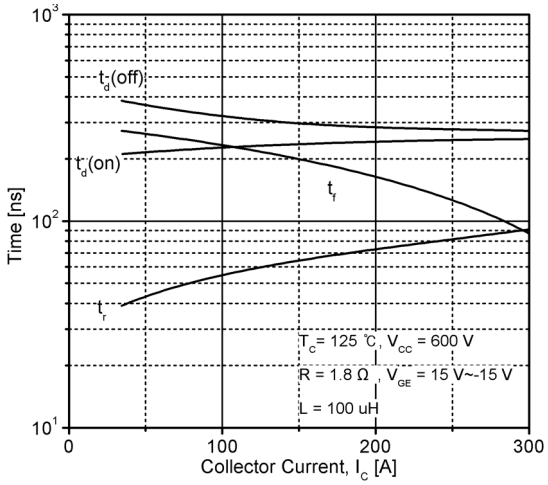


Fig 6. Typical Switching Time vs. Collector Current

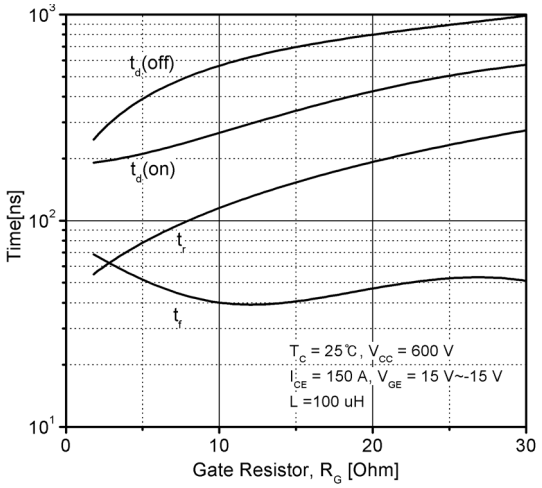


Fig 7. Typical Switching Time vs. Gate Resistor

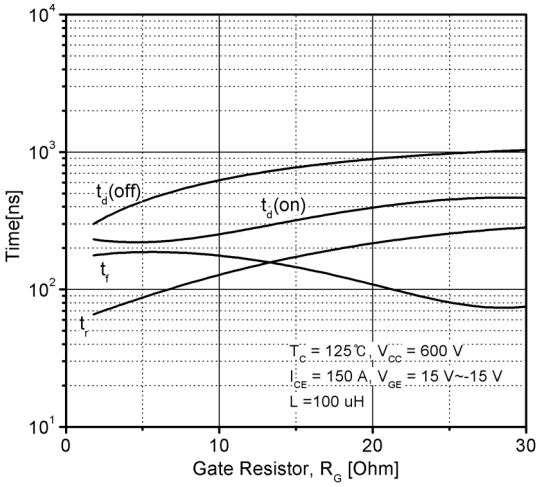


Fig 8. Typical Switching Time vs. Gate Resistor

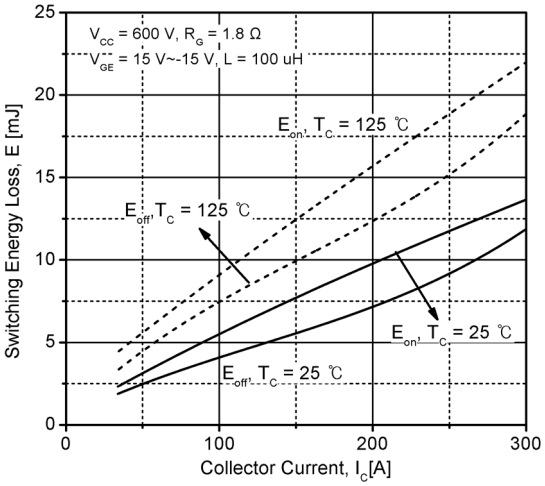


Fig 9. Typical IGBT Switching Loss

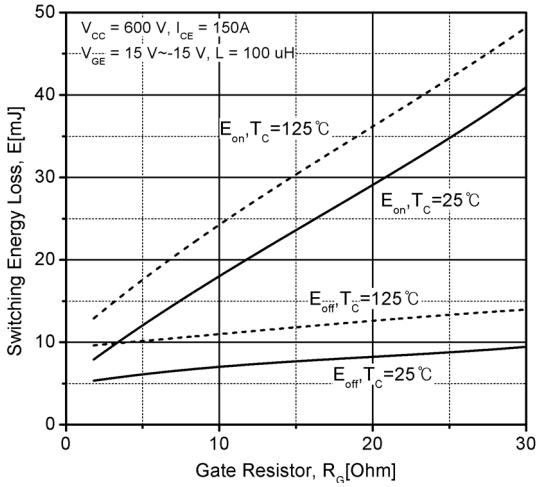


Fig 10. Typical IGBT Switching Loss

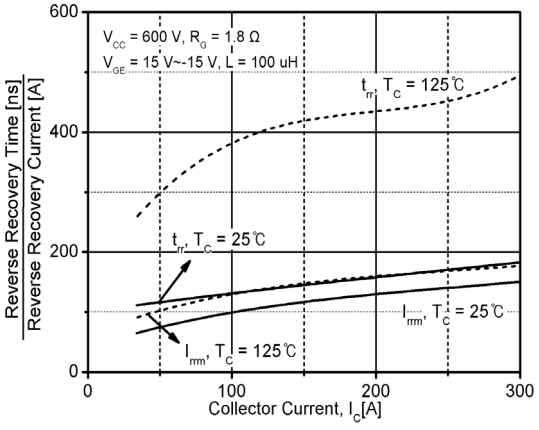


Fig 11. Typical Recovery Characteristics of Diode

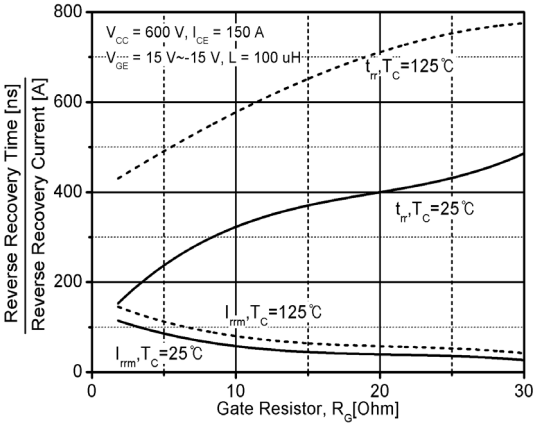


Fig 12. Typical Recovery Characteristics of Diode

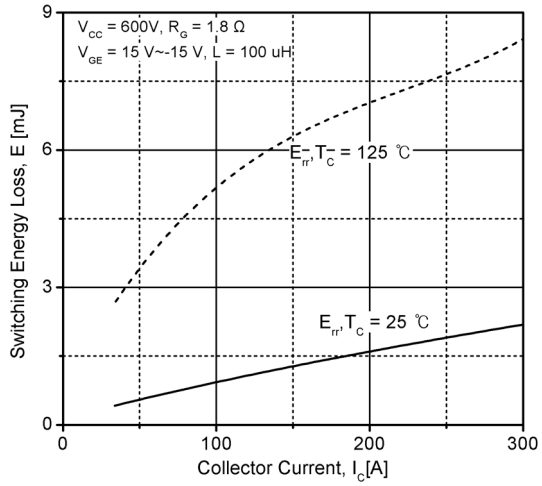


Fig 13. Typical Diode Switching Loss

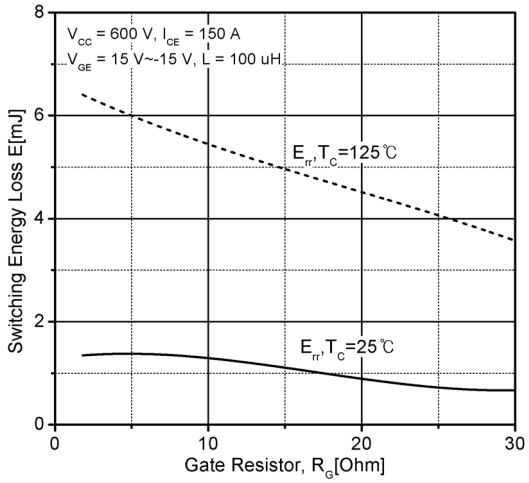


Fig 14. Typical Diode Switching Loss

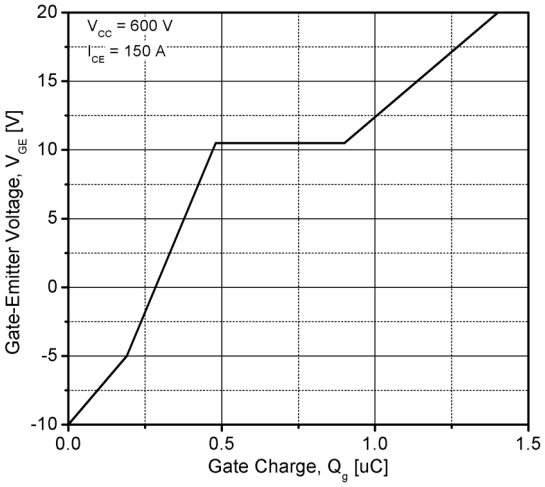


Fig 15. Typical Gate Charge Characteristics

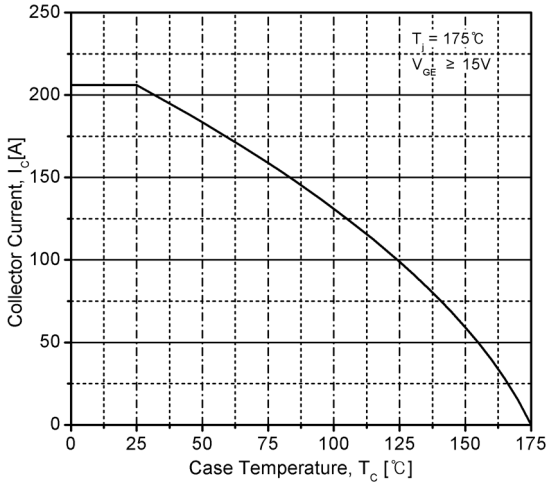


Fig 16. Case Temperature vs. Collector Current

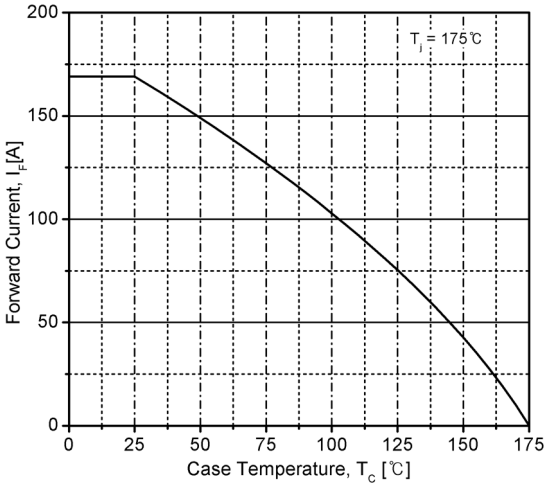


Fig 17. Case Temperature vs. Diode Current

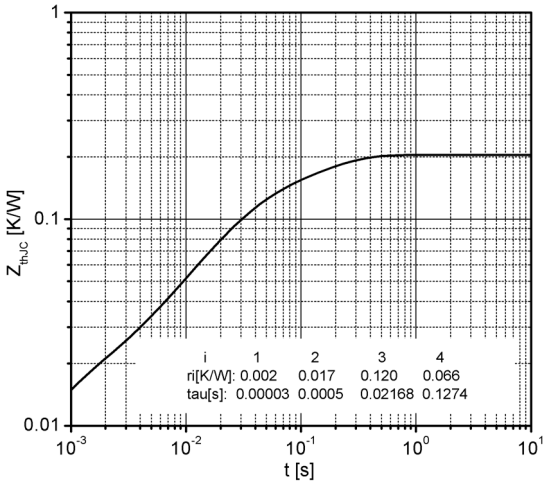


Fig 18. Typical IGBT Thermal Impedance

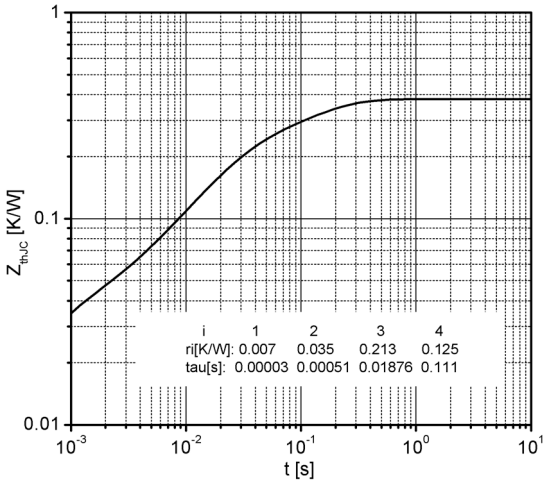
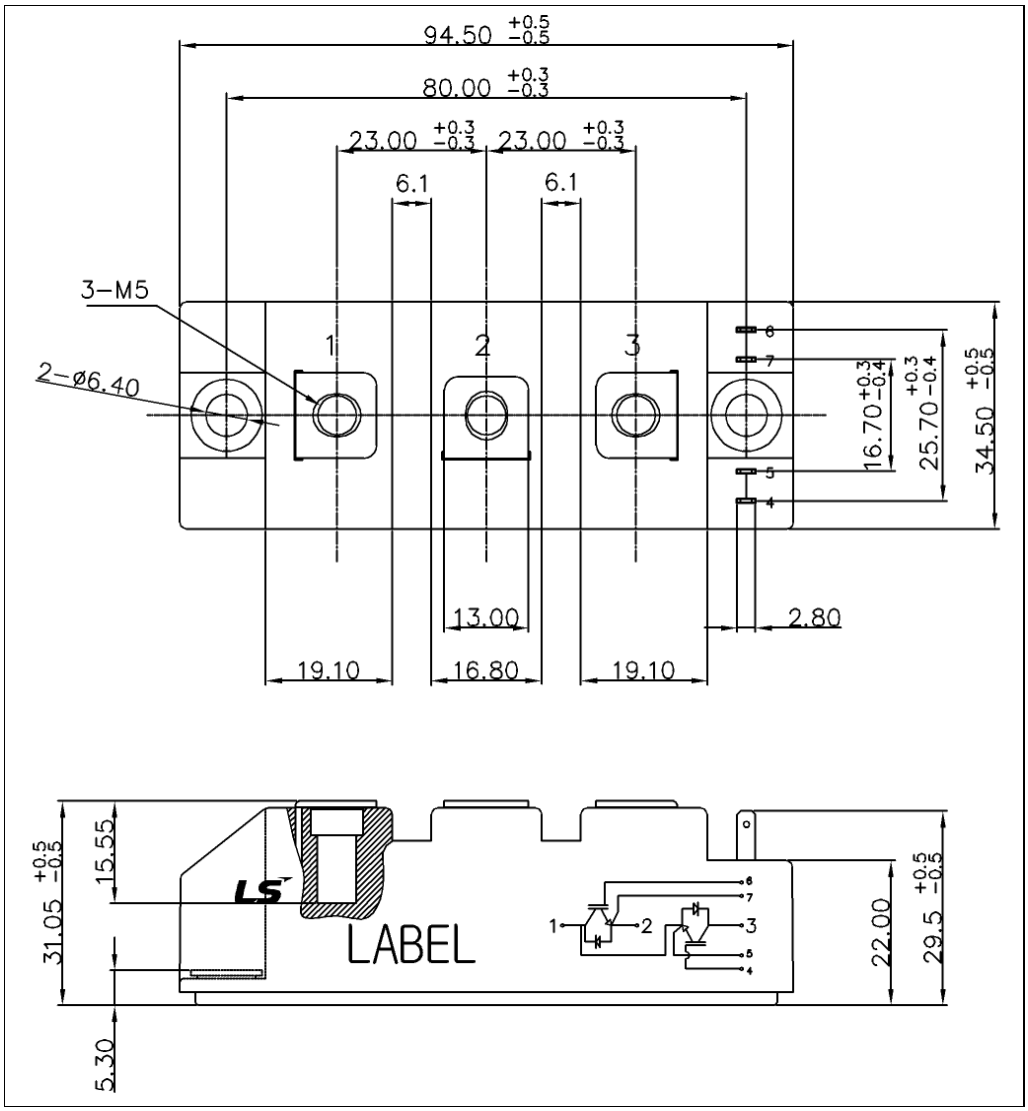


Fig 19. Typical Diode Thermal Impedance

Package Dimension(Dimension in mm)



Circuit Description